



2021 7th International Workshop on Low Temperature Bonding for 3D Integration

## Call for Papers

Abstract Due June 11, 2021

2021 7th International Workshop on Low Temperature Bonding  
for 3D Integration  
(LTB-3D 2021, WaferBond 2021 East)

Oct. 5-7, 2021 in Nara-city, Japan

Sponsored by

General Incorporated Non-profit Association - Institute for Advanced Micro-System Integration (IMSI)

Technically Co-sponsored by

The Electrochemical Society (to be confirmed)

IEEE Electronics Packaging Society Japan Chapter (to be confirmed)

Endorsed by

The Japan Society of Applied Physics (JSAP)



## 2021 7th International Workshop on Low Temperature Bonding for 3D Integration

2021 7th International Workshop on Low Temperature Bonding for 3D Integration (LTB-3D 2021) will be held from 5-7, Oct. 2021 in Nara-city, Japan.

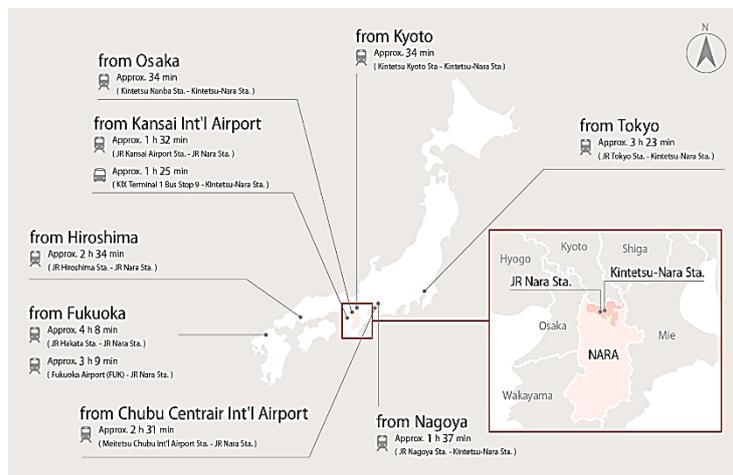
The LTB-3D is a premier conference series sponsored by General Incorporated Non-profit Association - Institute for Advanced Micro-System Integration (IMSI), technically co-sponsored by The Electrochemical Society and The IEEE EPS Japan Chapter. Preceding LTB-3D workshop was held in Tokyo, Japan in its 1st (2007), 2nd (2010), 3rd (2012), 4th (2014), and 5th (2017) versions and in Kanazawa in 6th (2019) version. LTB-3D 2021 moves to Nara, an ancient capital of Japan as WaferBond 2021 EAST in conjunction with WaferBond conferences which are held in Europe every two years: 2009 (Grenoble), 2011 (Chemnitz), 2013 (Stockholm), 2015 (Braunschweig), 2017 (Leuven), and 2019 (Halle/Saale).

This workshop is focusing on the promotion of advanced research areas related to low-temperature bonding technologies, including surface activated bonding (SAB), which realize novel device structure by heterogeneous material and device integration and lead to entirely new manufacturing approaches to 3D and module integration of semiconductor devices, photonics systems, and power electronic systems. These bonding technologies have been already used for the volume production and have potential applications in wide range of manufacturing industries. This workshop will be held as a single-track seminar to provide a compact forum for close and deep discussion of all aspects of low temperature bonding technologies — the latest technologies and applications, as well as business opportunities.

Professor Dr. Naoteru Shigekawa  
Osaka City University  
Steering Committee Chair

Professor Dr. Tadatomo Suga  
Meisei University / The University of Tokyo  
IMSI  
IEEE EPS Japan Chapter  
Lead Organizer, International Organizing Committee

### ● Access to Nara



### ● Venue

Nara Kasugano International Forum "IRAKA."



### ● Scope

- Roles of Low-temperature Bonding in 3D and Hetero-Integration
- Surface Activated Bonding (SAB) and its Extensions
- Hydrophilic and Plasma-assisted Bonding
- Metal and Hybrid Bonding
- New process for Low-temperature Bonding
- Power, RF, Photonic, and MEMS device Applications
- New Applications of Low-temperature Bonding
- Fundamentals and characterization
- Equipment and Quality Assessments

### ● Important Date

Abstract submission deadline ————— June 11th, 2021  
Acceptance/Rejection notification ————— July 16th, 2021  
Final manuscript and presentation material deadline  
————— Aug. 13th, 2021  
Conference ————— Oct. 5th–7th, 2021

### ● Satellite Workshop

Satellite Workshop composed of invited seminars will also be arranged online after LTB-3D 2021 so as to discuss hot topics and current trends in low temperature bonding.

### ● JJAP Special Issue

Special Issue of Japanese Journal of Applied Physics will be published as journal related to LTB-3D 2021 and Satellite Workshop.

- For further information, get in touch with <https://imsi.jp/ltb3d/ltb3d-2021/index.html>